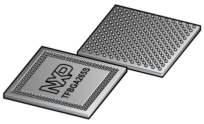

SOT1865-1

TFBGA265S, plastic thin fine-pitch ball grid array; 265 balls, 0.75 mm interstitial pitch, 13 mm x 13 mm x 1.04 mm body

20 September 2018 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA265S
Package type industry code	TFBGA265S
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-09-2018
Manufacturer package code	98ASA00966D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	13	-	mm
package width	-	13	-	mm
seated height	-	1.04	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	265	-	

2 Package outline

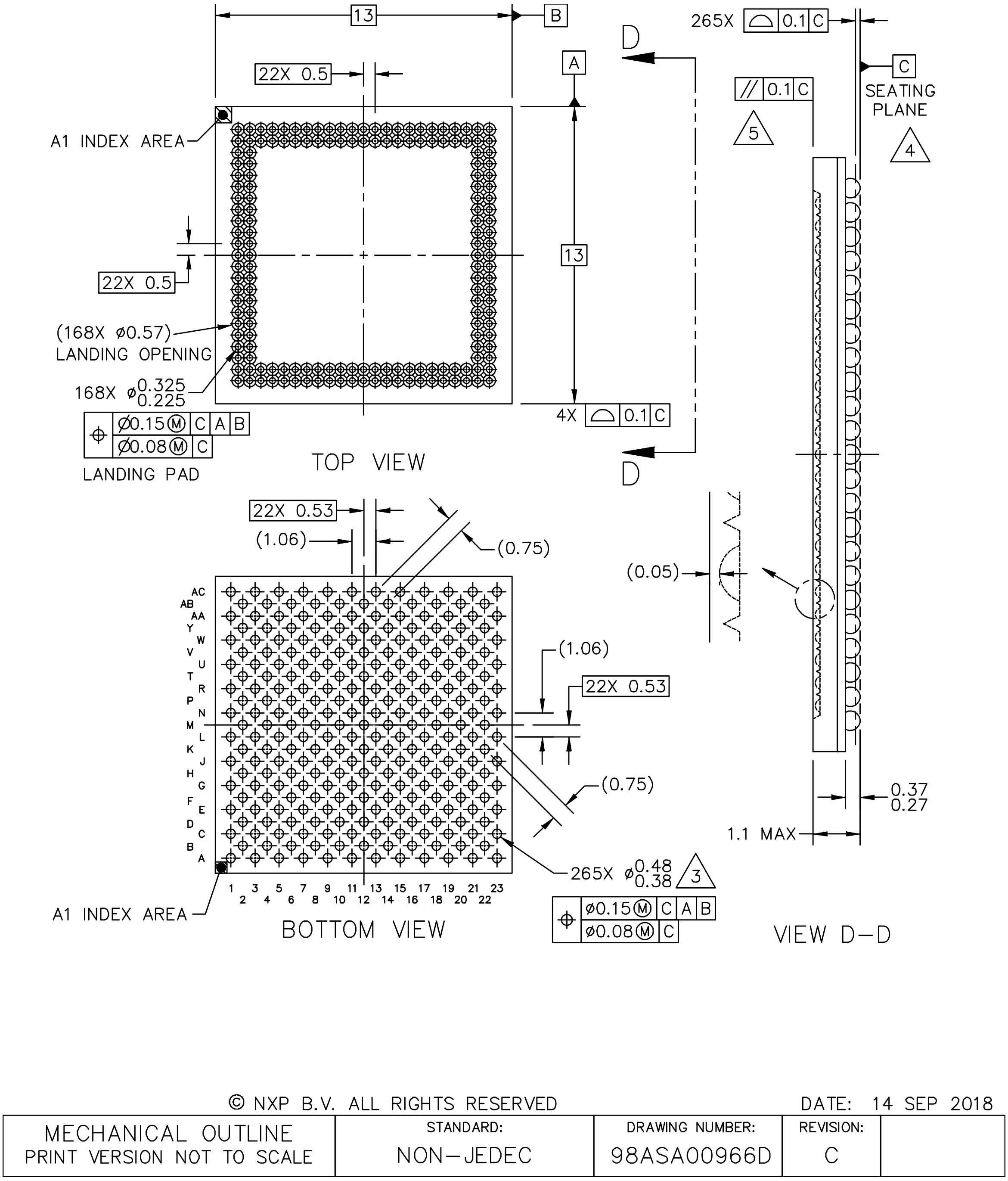

Figure 1. Package outline TFBGA265S (SOT1865-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. △ MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. △ DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. △ PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. SCORING OR GROOVES ON TOP SURFACE OF PACKAGE IS NOT PERMITTED.
7. NO VOIDS IN ENCAPSULATION PERMITTED.

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DATE: 14 SEP 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA00966D	REVISION: C	

Figure 2. Package outline note TFBGA265S (SOT1865-1)

3 Legal information

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